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JIS

JAPANESE INDUSTRIAL STANDARD

General rules of copper-clad laminates for printed wiring boards

JIS C 6480–1994

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General rules of copper-clad laminates for printed wiring boards

C 6480-1994

1. Scope This Japanese Industrial Standard specifies the basic matters for determination of classes, performances, marking, etc. of copper-clad laminates for printed wiring boards, and multilayer printed wiring boards (hereafter referred to as "copper-clad laminates").

Remarks: The following standards are cited in this Standard:

JIS C 5603 Terms and definitions for printed circuits

JIS C 6481 Test methods of copper-clad laminates for printed wiring boards

JIS C 6511 Test methods of copper foil for printed wiring boards

2. Definitions For the purposes of this Standard, the definitions given in JIS C 5603 apply.

3. Type designation

3.1 Structure of type designation The type designation shall be formed by arranging the symbols as follows:

[Symbol denoting class of copper-clad laminate]	[Hyphen]	[Symbol denoting base material and resin]	[Symbol denoting characteristics]	[Symbol denoting thickness and cladding of copper foil]	[Symbol denoting size]	[Symbol denoting thickness]	[Hyphen]
[3.2.1]		[3.2.2]		[3.2.3]	[3.2.4]	[3.2.5]	

Example:

FCL	—	GE	4F	18/18	A	16	—

[Symbol denoting tolerance on thickness]	[Symbol denoting appearance]	[Symbol denoting flame retardance]
[3.2.6]	[3.2.7]	[3.2.8]
1	2	V0

3.2 Symbols

3.2.1 Class of copper-clad laminates The symbol denoting copper-clad laminates for printed wiring boards shall be English capital letters of FCL, and the symbol denoting copper-clad laminates for multilayer printed wiring boards shall be English capital letters of TCL.

3.2.2 Base material, resin and characteristics The symbol denoting base material, resin, and characteristics shall consist of a combination of two English capital letters and one numeral for single base material, shall consist of a combination of three English capital letters and one numeral for composite base materials, and flame retardance shall be denoted by the English capital letter F following to the numeral in the symbol denoting characteristics as given in Table 1.

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